

**FGA25N120AN****General Description**

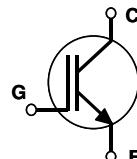
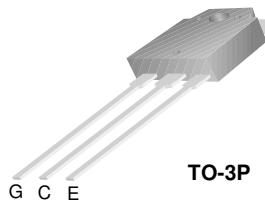
Employing NPT technology, Fairchild's AN series of IGBTs provides low conduction and switching losses. The AN series offers a solution for application such as induction heating (IH), motor control, general purpose inverters and uninterruptible power supplies (UPS).

**Features**

- High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.5 \text{ V}$  @  $I_C = 25\text{A}$
- High input impedance

**Applications**

Induction Heating, UPS, AC & DC motor controls and general purpose inverters.

**Absolute Maximum Ratings**

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Description	FGA25N120AN	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C = 25^\circ\text{C}$	40	A
	Collector Current @ $T_C = 100^\circ\text{C}$	25	A
$I_{CM(1)}$	Pulsed Collector Current	75	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	310	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	125	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

**Notes :**

(1) Repetitive rating : Pulse width limited by max. junction temperature

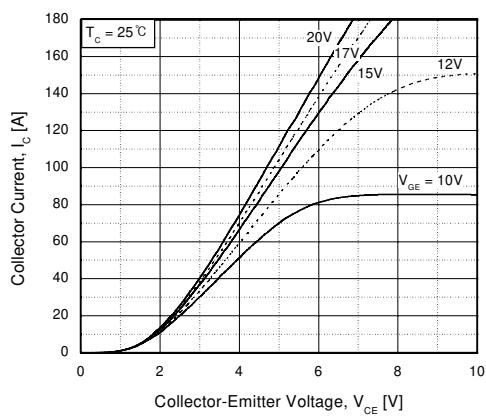
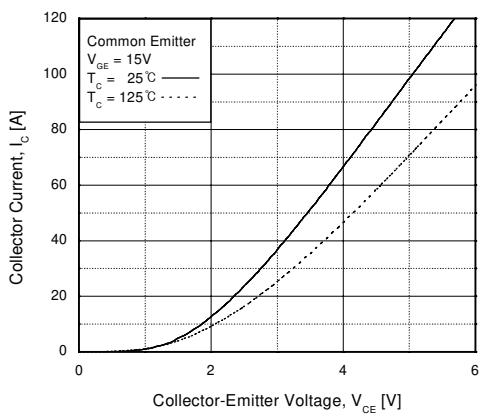
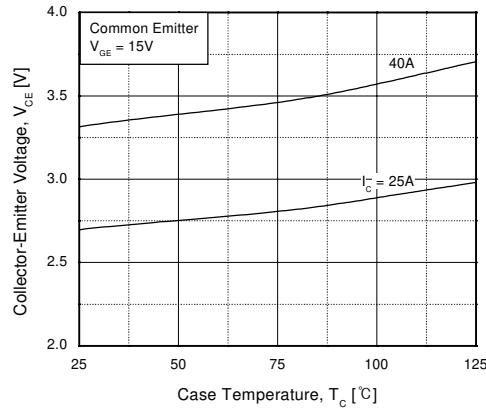
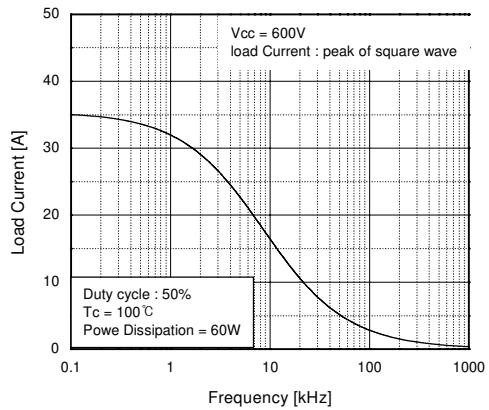
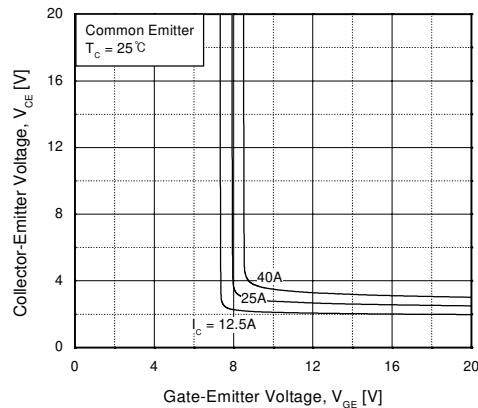
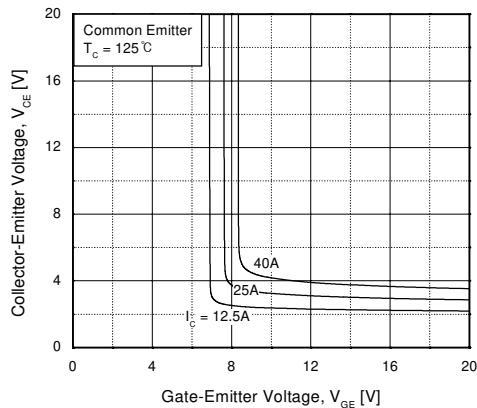
**Thermal Characteristics**

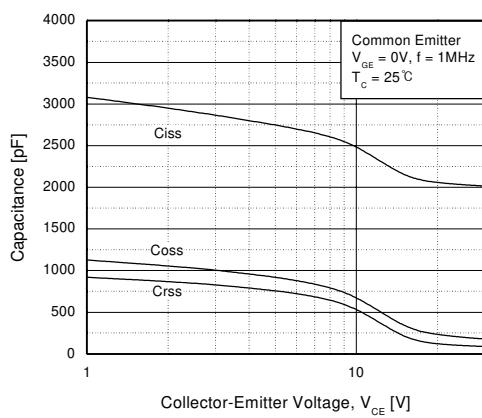
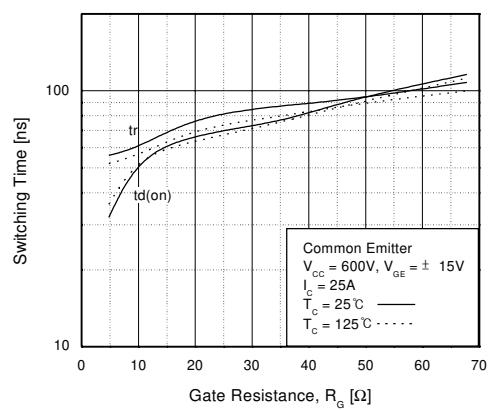
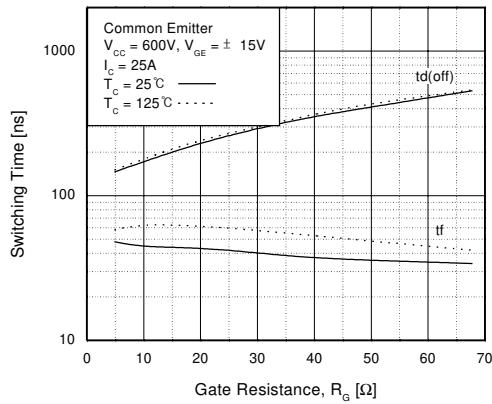
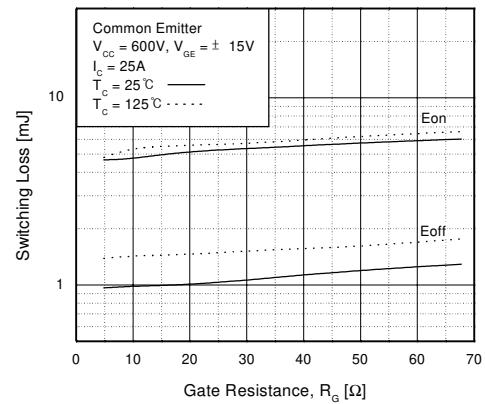
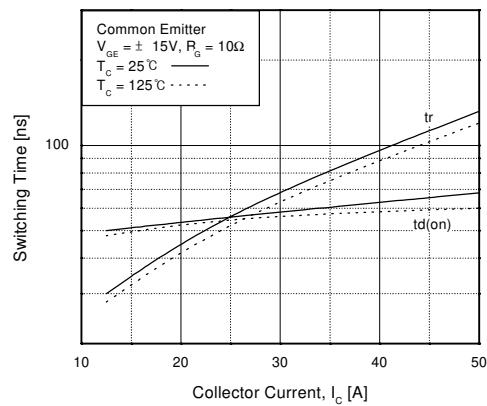
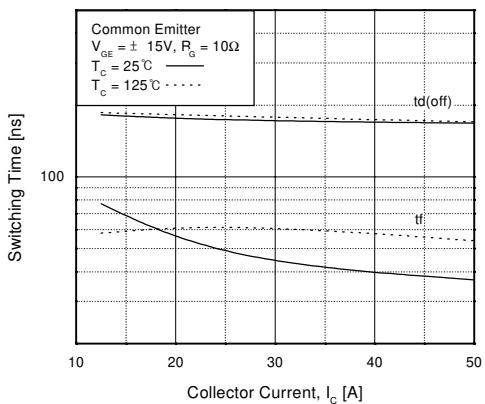
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	0.4	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	$^\circ\text{C}/\text{W}$

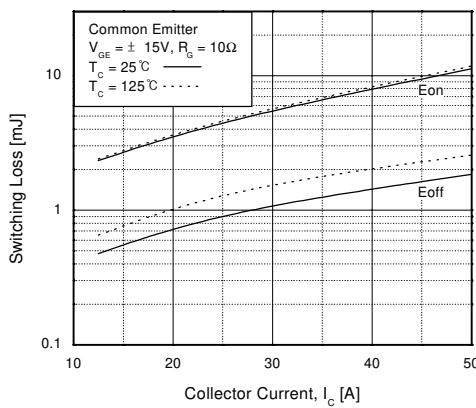
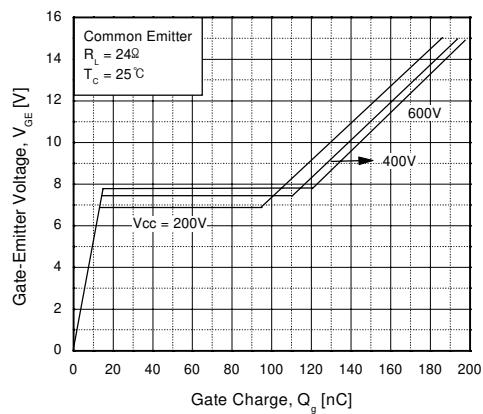
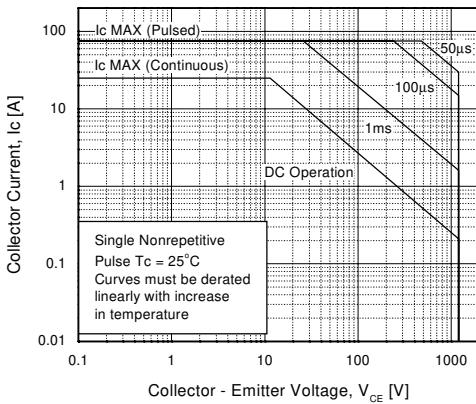
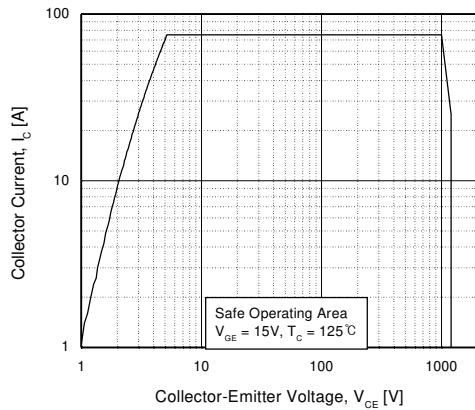
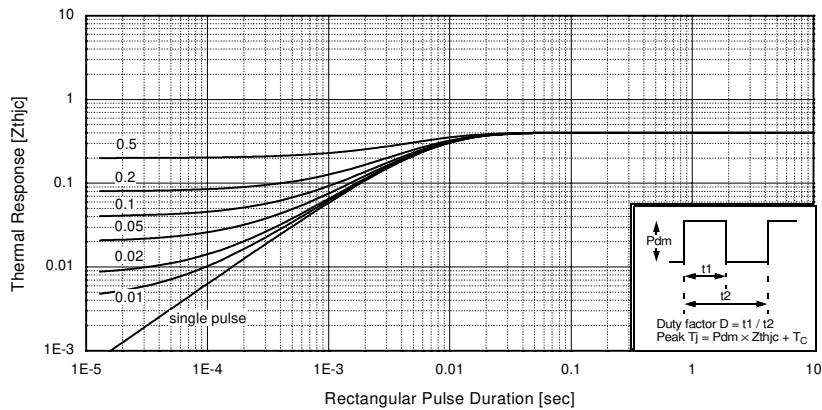
## Electrical Characteristics of the IGBT

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 3\text{mA}$	1200	--	--	V
$\Delta BV_{CES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0\text{V}, I_C = 3\text{mA}$	--	0.6	--	$\text{V}/^\circ\text{C}$
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0\text{V}$	--	--	3	mA
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0\text{V}$	--	--	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GE(\text{th})}$	G-E Threshold Voltage	$I_C = 25\text{mA}, V_{CE} = V_{GE}$	3.5	5.5	7.5	V
$V_{CE(\text{sat})}$	Collector to Emitter Saturation Voltage	$I_C = 25\text{A}, V_{GE} = 15\text{V}$	--	2.5	3.2	V
		$I_C = 25\text{A}, V_{GE} = 15\text{V}, T_C = 125^\circ\text{C}$	--	2.9	--	V
		$I_C = 40\text{A}, V_{GE} = 15\text{V}$	--	3.1	--	V
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE} = 30\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	--	2100	--	pF
$C_{oes}$	Output Capacitance		--	180	--	pF
$C_{res}$	Reverse Transfer Capacitance		--	90	--	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 600\text{ V}, I_C = 25\text{A}, R_G = 10\Omega, V_{GE} = 15\text{V}, \text{Inductive Load}, T_C = 25^\circ\text{C}$	--	60	--	ns
$t_r$	Rise Time		--	60	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	170	--	ns
$t_f$	Fall Time		--	45	90	ns
$E_{on}$	Turn-On Switching Loss		--	4.8	7.2	mJ
$E_{off}$	Turn-Off Switching Loss		--	1.0	1.5	mJ
$E_{ts}$	Total Switching Loss		--	5.7	8.7	mJ
$t_{d(on)}$	Turn-On Delay Time		--	60	--	ns
$t_r$	Rise Time		--	60	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	180	--	ns
$t_f$	Fall Time	$V_{CC} = 600\text{ V}, I_C = 25\text{A}, R_G = 10\Omega, V_{GE} = 15\text{V}, \text{Inductive Load}, T_C = 125^\circ\text{C}$	--	70	--	ns
$E_{on}$	Turn-On Switching Loss		--	5.5	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	1.4	--	mJ
$E_{ts}$	Total Switching Loss		--	6.9	--	mJ
$Q_g$	Total Gate Charge		--	200	300	nC
$Q_{ge}$	Gate-Emitter Charge	$V_{CE} = 600\text{ V}, I_C = 25\text{A}, V_{GE} = 15\text{V}$	--	15	23	nC
$Q_{gc}$	Gate-Collector Charge		--	105	160	nC
$L_e$	Internal Emitter Inductance	Measured 5mm from PKG	--	14	--	nH


**Fig 1. Typical Output Characteristics**

**Fig 2. Typical Saturation Voltage Characteristics**

**Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level**

**Fig 4. Load Current vs. Frequency**

**Fig 5. Saturation Voltage vs.  $V_{GE}$** 

**Fig 6. Saturation Voltage vs.  $V_{GE}$**

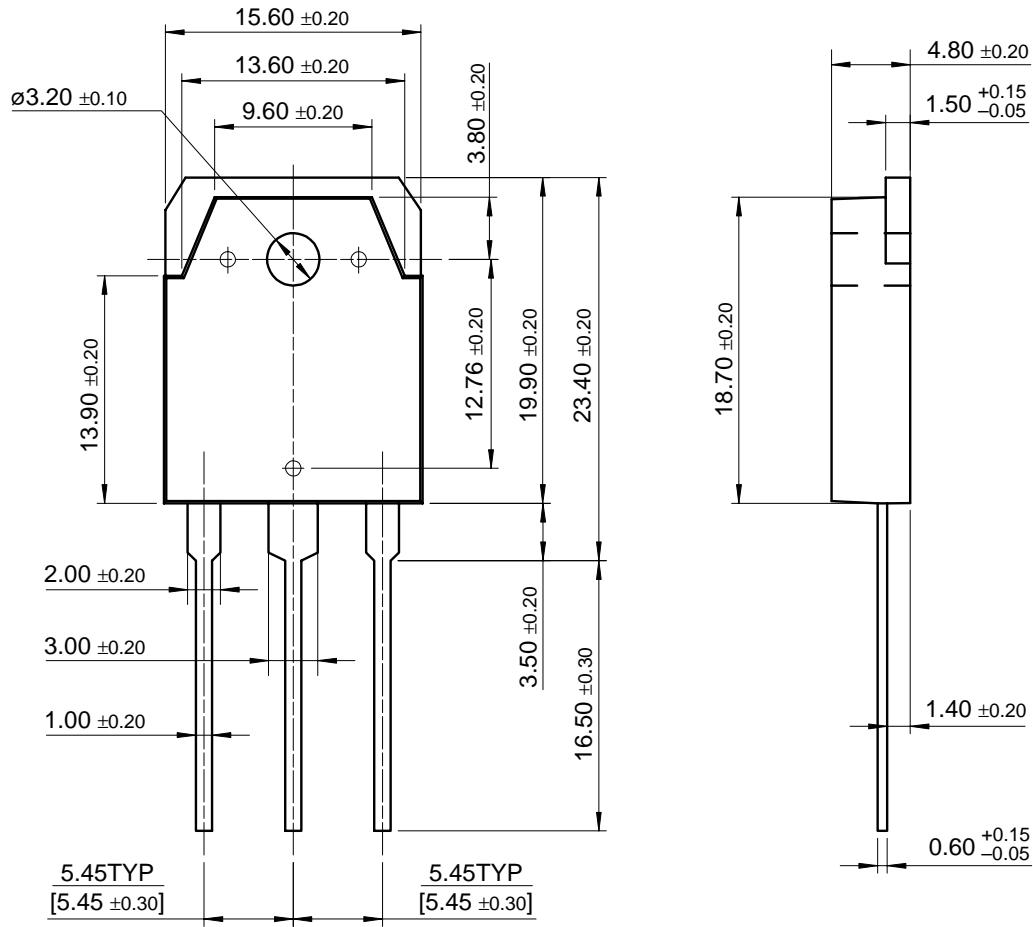

**Fig 7. Capacitance Characteristics**

**Fig 8. Turn-On Characteristics vs. Gate Resistance**

**Fig 9. Turn-Off Characteristics vs. Gate Resistance**

**Fig 10. Switching Loss vs. Gate Resistance**

**Fig 11. Turn-On Characteristics vs. Collector Current**

**Fig 12. Turn-Off Characteristics vs. Collector Current**


**Fig 13. Switching Loss vs. Collector Current**

**Fig 14. Gate Charge Characteristics**

**Fig 15. SOA Characteristics**

**Fig 16. Turn-Off SOA**

**Fig 17. Transient Thermal Impedance of IGBT**

**FGA25N120AN**

**Package Dimension**

**TO-3P (FS PKG CODE)**



Dimensions in Millimeters

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